

SPECIFICATION

Please amend paragraph 10 as follows:

[0001]

Another method is to attach the silicone chip to a temperature resistant substrate, like alumina ceramics, FR4 (PCB) or similar material, which includes metalized pads for soldering to the optical system's PCB. After wire-bond connections, the top of this assembly is covered by a transparent plastic layer, protecting the silicon chip and wire-bond areas. Such a light detector 16 is illustrated in Figure 2 as including a substrate 20 having an integrated circuit 22, including a light detector mounted thereon. Metalized pads 24 on the substrate 20 are connected by wires 26 to bonding pads on the integrated circuit 22. A plastic protective layer or housing 30 encapsulates the integrated circuit 22 and wires 26 and includes a window portion 32 provided in the ~~cover 22~~ housing 30. A protective coating 34 is provided over the plastic window 32.